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JUL 1 8 2005

Docket No. 59744 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

C. Huang et al.

U.S. SERIAL NO:

10/643,375

**FXAMINER: D. Owens** 

FILED:

August 18, 2003

GROUP:

FOR:

entered by RCE filed 7/18/05 Shaws ON 8/24/05 SEMICONDUCTOR PACKAGE HAVING CONDUCTIVE BUMPS ON

CHIP AND METHOD FOR FABRICATING THE SAME

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on July 18, 2005.

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

## AMENDMENT

Applicants are in receipt of the Office Action dated April 18, 2005 of the abovereferenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.